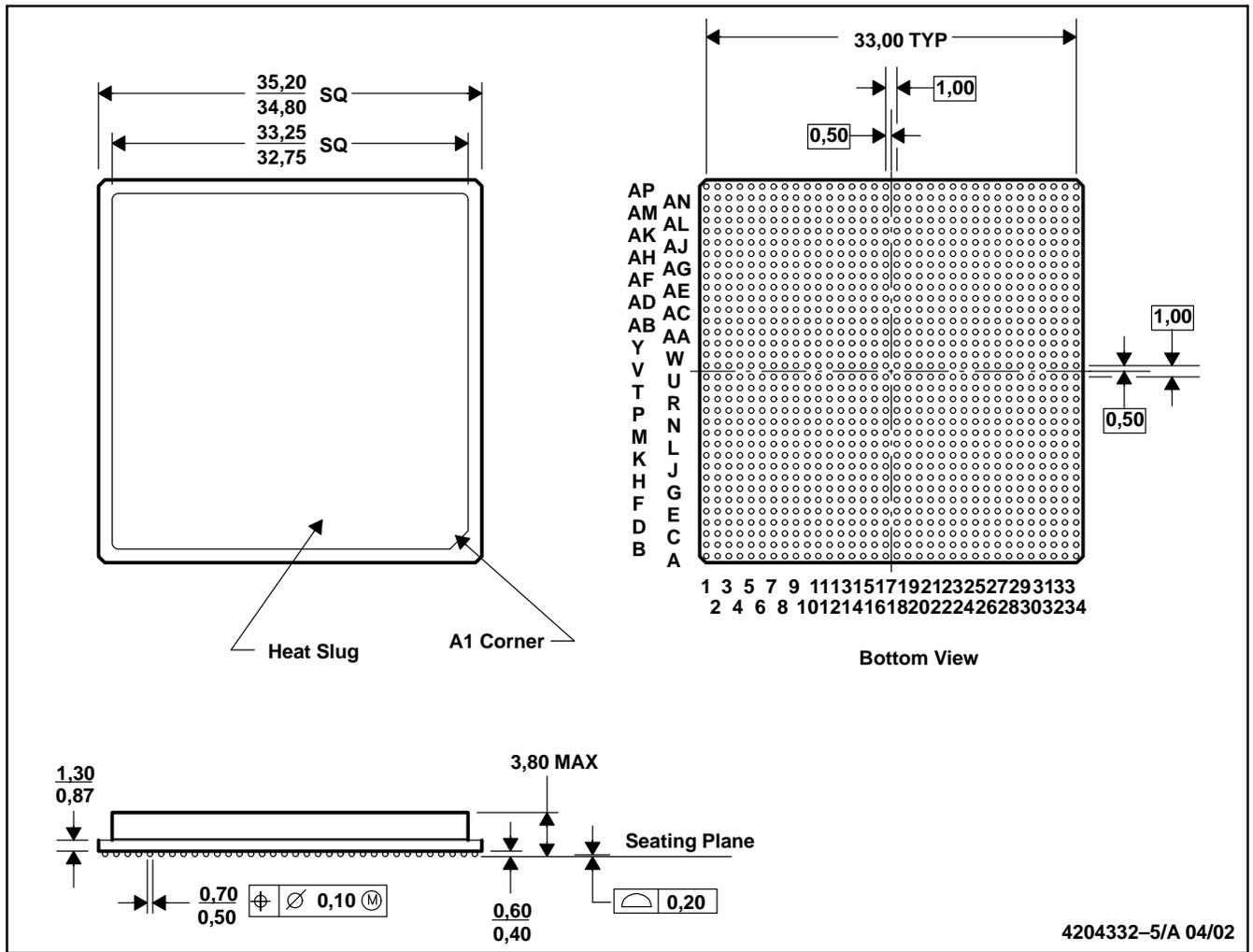


GDN (S-PBGA-N1156)

PLASTIC BALL GRID ARRAY



4204332-5/A 04/02

- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Flip chip application only.

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